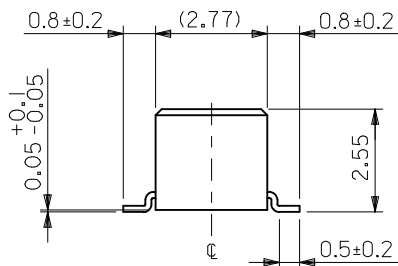
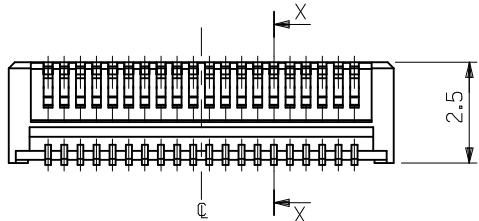


参考基板レイアウト (マウント面)
RECOMMENDED P.C.BOARD
PATTERN DIMENSION. (REF.)
(MOUNTING AREA)

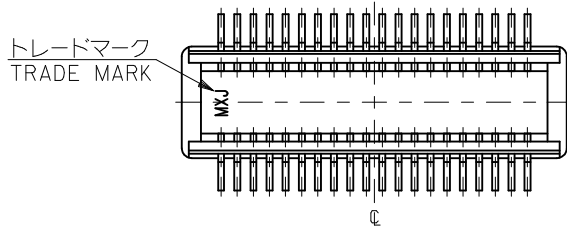


注記 NOTES:

- 使用材料 MATERIAL
ウエハー: 液晶ポリマー ガラス充填 UL94V-0 茶色
WAFER: LIQUID CRYSTAL POLYMER
GLASS FILLED UL94V-0
COLOR BROWN
ピン: リン青銅 (t=0.15)
PIN: PHOSPHOR BRONZE (t=0.15)
- メッキ仕様 PLATING
金メッキ 0.25 マイクロメートル以上 (コンタクト部)
GOLD 0.25MICROMETER MINIMUM (CONTACT AREA)
金メッキ 0.4 マイクロメートル以下 (テール部)
GOLD 0.4MICROMETER MAXIMUM (TAIL AREA)
下地メッキ: ニッケルメッキ 1.5 マイクロメートル以上
UNDER PLATING: NICKEL 1.5MICROMETER MINIMUM

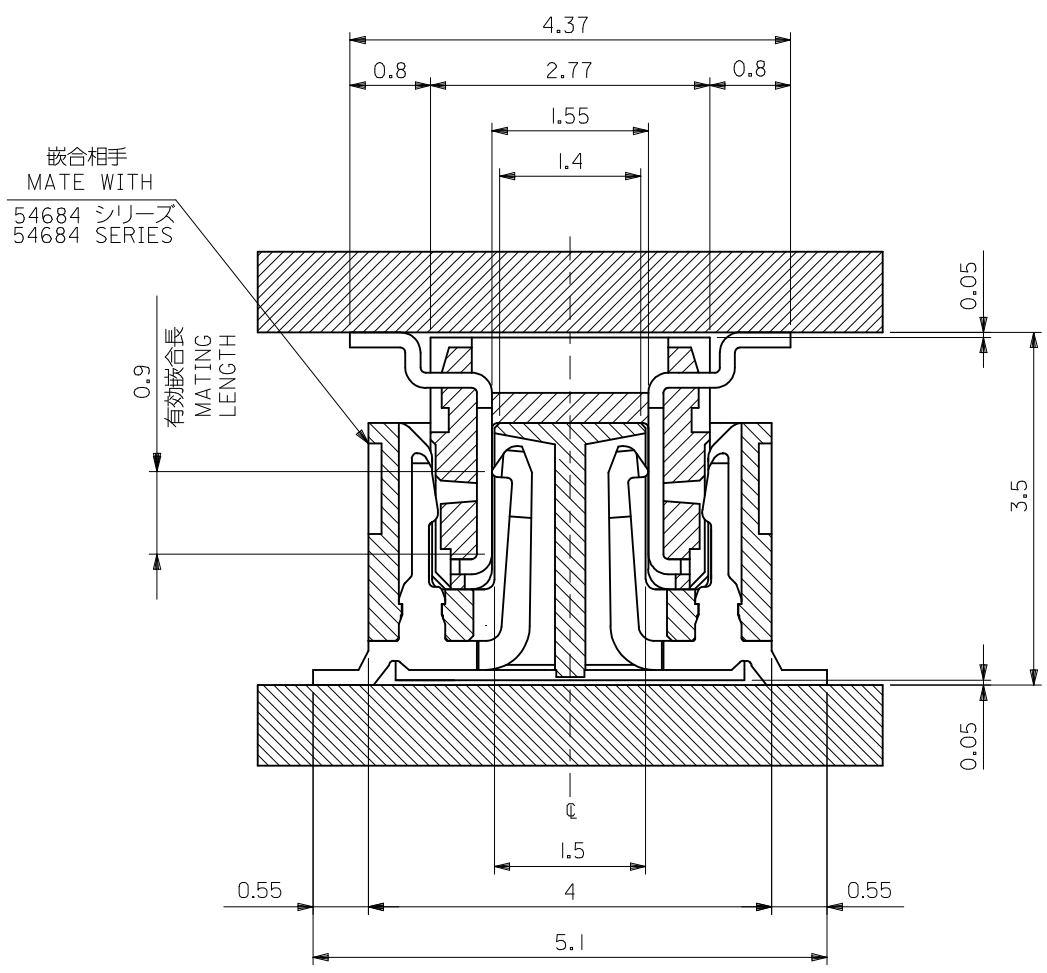
- (全極数/2) = 偶数の場合に適用。
APPLY FOR (CIRCUIT/2) = EVEN.
- 嵌合相手: 54684 シリーズ
MATE WITH: 54684 SERIES.
- テール平坦度は、0.08 以下
TAIL COPLANARITY TO BE 0.08 MAXIMUM.

無鉛
LEAD FREE



16.62	15.6	17.55	55526-0807	80
C	B	A	MATERIAL NO. CIRCUIT	
			MODEL NO.	55526-***7

MATERIAL 材料 注記参照 SEE NOTES	REVISED EC NO: J2016-0892 DRWN: YSHIDA 2016/02/22 CHKD: KANAKA03 2016/02/22 APP: K MORIKAWA 2016/02/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	±0.03	DRAWN BY S. AIHARA	DATE 1999/10/02	TITLE 0.4MM B-TO-B CONN PLUG NO BOSS (HGT=3.5MM)		
FINISH 仕上げ 注記参照 SEE NOTES	D	0.25 OVER	0.5 UNDER	±0.05	CHECKED BY T. ITO	DATE 2002/03/11	molex		DOCUMENT NO. SD-55526-003
		0.5 OVER	1.0 UNDER	±0.1	APPROVED BY T. YAMAGU	DATE 2002/03/11			
		1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		SHEET NO.		
		10 OVER	30 UNDER	±0.25	SEE CHART		1 OF 2		
		30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
		ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS					

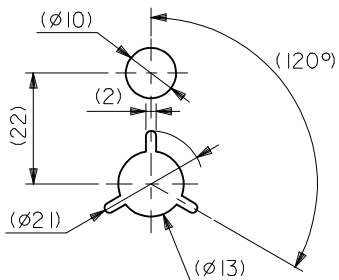
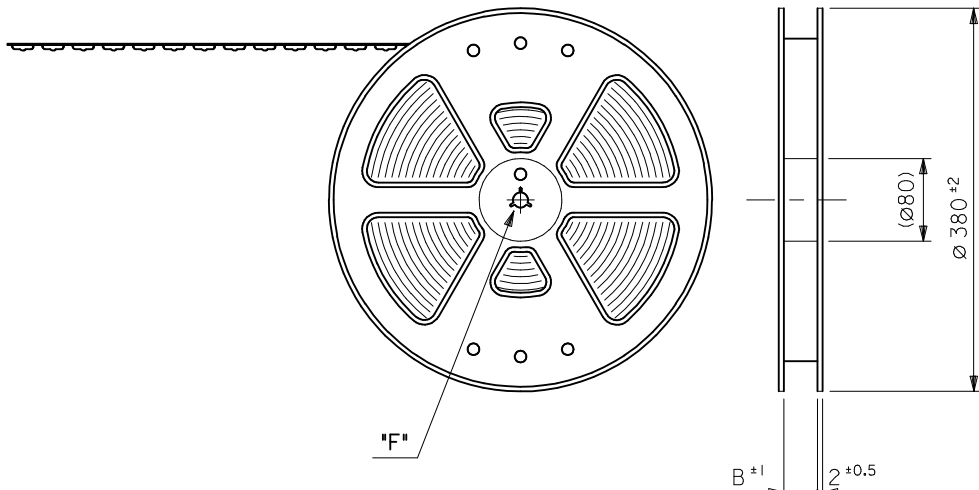


嵌合断面図 (参考)
MATED DRAWING (REF.)

無鉛
LEAD FREE

MATERIAL 材料	REVISED EC NO: J2016-0892 DRWN: Y. SHIDA 2016/02/22 CHKD: K. TANAKA 2016/02/22 APPR: K. MORIKAWA 2016/02/29	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO. 55526-***7
		0.25 UNDER	UNDER	±---	DRAWN BY S. AIHARA	DATE 1999/10/02	TITLE 0.4MM B-TO-B CONN PLUG NO BOSS (HGT=3.5MM)	THIRD ANGLE PROJECTION
		0.25 OVER	0.5 UNDER	±---	CHECKED BY T. ITO	DATE 2002/03/11	molex	DOCUMENT NO. SD-55526-003
		0.5 OVER	1.0 UNDER	±---	APPROVED BY T. YAMAGU	DATE 2002/03/11		
SHEET 1 OF 2 参照 REFER TO SHEET 1 OF 2		1.0 OVER	10 UNDER	±---	SEE CHART		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	
		30 OVER	±---	SIZE A3				
		ANGULAR	±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

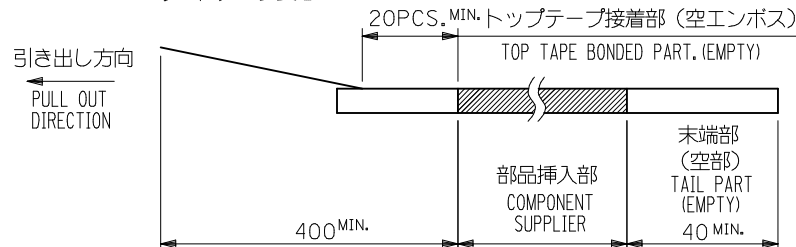
引き出し方向
PULL OUT
DIRECTION



DETAIL "F"

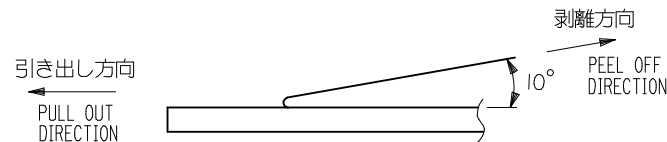
NOTES

- 製品詳細寸法については図面 SD-55526-003 を参照下さい。
RE DETAILED DIMENSION, SEE SD-55526-003
- 梱包数量：1500個/リール
NUMBER OF CONNECTORS : 1500PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度：0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(剥離方向は下図参照)

尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE : 0.1N ~ 0.7N(10.2gf ~ 71.4gf)
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED , DURING TRANSPORTATION.



- 材料(MATERIAL)
キャリアテープ(CARRIER TAPE): ポリプロピレン(POLYPROPYLENE)
トップテープ(TOPTAPE): PET, PE, PEF
リール(REEL): ポリスチレン(P.S) <リサイクル材を含む>
POLYSTYREN(PS) <RECYCLE MATERIAL CONTAINED>

無鉛
LEAD FREE

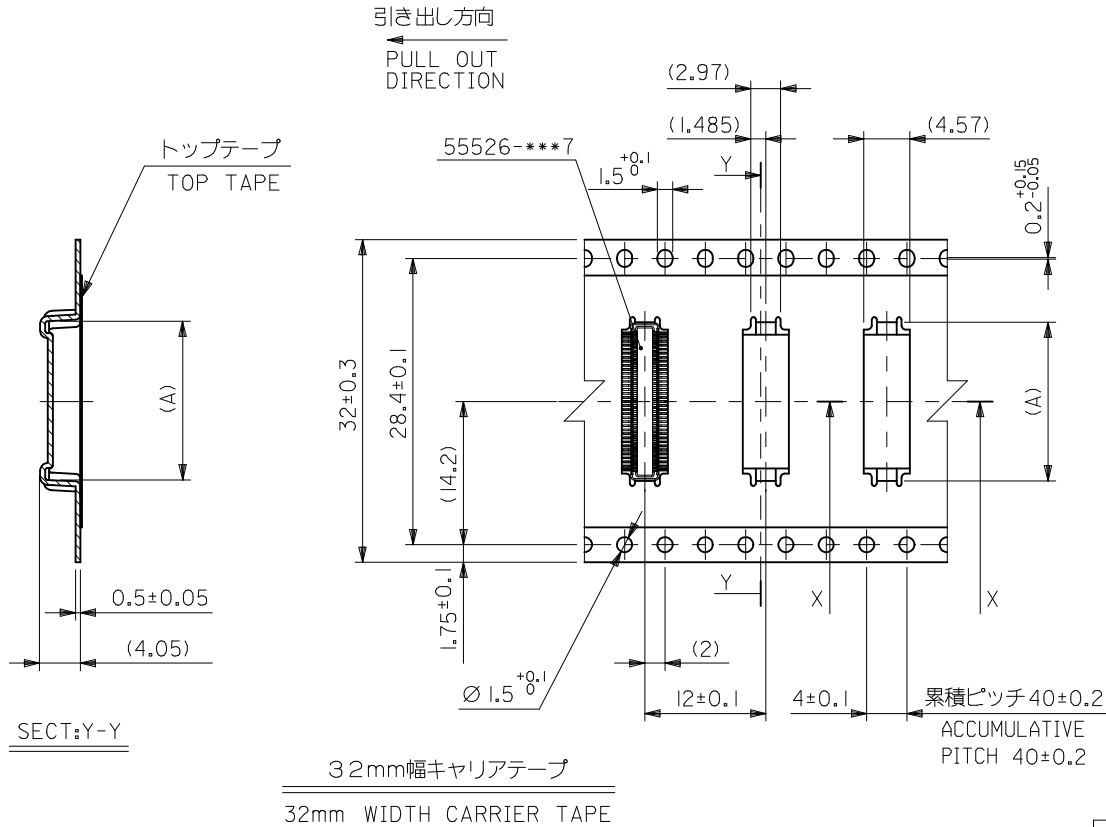
MATERIAL 材料	注記参照 SEE NOTES
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REVISED	EC NO: J2012-0554	2011/09/08	GENERAL TOLERANCES (UNLESS SPECIFIED)
DRWN: YON002	2011/09/08	2011/09/08	10 UNDER ±0.2
CHKD: TASAKAWA	2011/09/08	2011/09/08	10 OVER 30 UNDER ±0.25
APPR: MSASAO	2012/07/06	2012/07/06	30 OVER ±0.3
DESCRIPTION			ANGULAR ±3 °
REV			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	
DRAWN BY S. AIHARA	DATE 1999/10/02
CHECKED BY T. ITO	DATE 2002/03/11
APPROVED BY T. YAMAGU	DATE 2002/03/11
MATERIAL NO. SEE CHART	
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SCALE ---	DESIGN UNITS METRIC	MODEL NO. 55526-***8
TITLE 0.4MM B-TO-B CONN PLUG NO BOSS (HGT=3.5MM) EMBSTP PKG		THIRD ANGLE PROJECTION
DOCUMENT NO. SD-55526-004		SHEET NO. 1 OF 3

molex



無鉛
LEAD FREE

32	33.5	17.75	55526-0808	80
キャリアテープ幅 CARRIER TAPE WIDTH	B	(A)	MATERIAL NO.	極数 CKT.

MATERIAL
材料

SHEET 1 OF 3 参照
REFER TO SHEET 1 OF 3

REVISED
EC NO: J2012-0554
DRWN: YON002
CHKD: TASAKAWA
APPR: MSASAO

2011/09/08
2011/09/08
2012/07/06

GENERAL TOLERANCES
(UNLESS SPECIFIED)

10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR	±3 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

DRAWN BY T. TSUBOI	DATE 2002/03/11
CHECKED BY T. ITO	DATE 2002/03/11
APPROVED BY T. YAMAGU	DATE 2002/03/11

MATERIAL NO.
SEE CHART

MODEL NO. 55526-***8

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

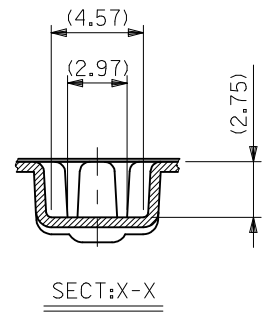
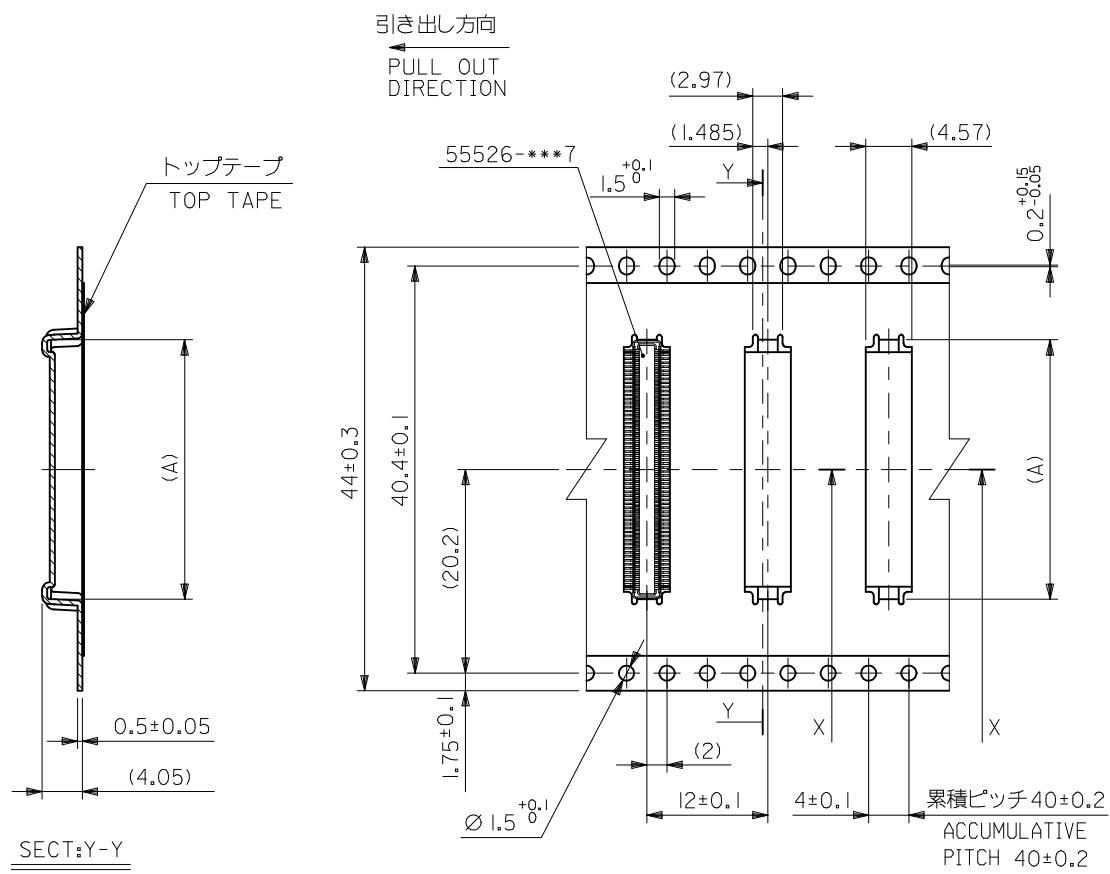
0.4MM B-TO-B CONN
PLUG NO BOSS (HGT=3.5MM)
EMBSTP PKG

molex

DOCUMENT NO. SD-55526-004

SHEET NO. 2 OF 3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX
INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION



SECT:Y-Y

44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

累積ピッチ 40±0.2
ACCUMULATIVE PITCH 40±0.2

無鉛
LEAD FREE

44	45.5	25.75	55526-1208	120
キャリアテープ幅 CARRIER TAPE WIDTH	B	(A)	MATERIAL NO.	極数 CKT.

MATERIAL
材料

SHEET 1 OF 3 参照
REFER TO SHEET 1 OF 3

REVISED EC NO: J2012-0554 DRWN: YONOO2 CHKD: TASAKAWA APPR: MSASAO	2011/09/08	2011/09/08	2012/07/06
	DESCRIPTION		
	REV		

GENERAL TOLERANCES (UNLESS SPECIFIED)	
10 UNDER	±0.2
10 OVER 30 UNDER	±0.25
30 OVER	±0.3
ANGULAR ±3 °	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	MODEL NO. 55526-***8
DRAWN BY S. AIHARA	DATE 1999/10/02	TITLE 0.4MM B-TO-B CONN PLUG NO BOSS (HGT=3.5MM) EMBSTP PKG	THIRD ANGLE PROJECTION
CHECKED BY T. ITO	DATE 2002/03/11	molex	
APPROVED BY T. YAMAGU	DATE 2002/03/11		
MATERIAL NO.	DOCUMENT NO. SD-55526-004	SHEET NO. 3 OF 3	
SEE CHART			
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			